



SPN4814

N-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPN4814 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application , notebook computer power management and other battery powered circuits where high-side switching .

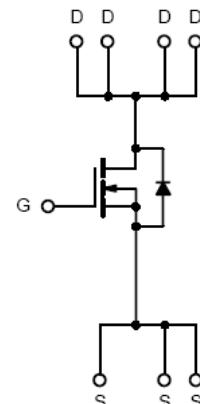
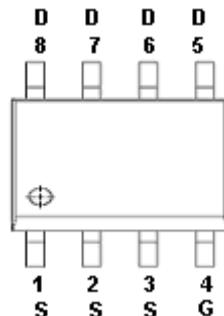
FEATURES

- ◆ 100V/20A,RDS(ON)=9.8mΩ@VGS=10V
- ◆ 100V/20A,RDS(ON)=13.0mΩ@VGS=4.5V
- ◆ Super high density cell design for extremely low RDS (ON)
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ SOP-8 package design

APPLICATIONS

- DC/DC Converter
- Load Switch
- Synchronous Buck Converter
- SMPS Secondary Side Synchronous Rectifier
- Power Tool
- Motor Control

PIN CONFIGURATION(SOP-8)



PART MARKING





SPN4814

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PIN DESCRIPTION

Pin	Symbol	Description
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN4814S8RGB	SOP-8	SPN4814

※ SPN4814S8RGB : 13" Tape Reel ; Pb – Free ; Halogen – Free

ABSOLUTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	100	V
Gate –Source Voltage	V _{GSS}	±20	V
Continuous Drain Current(T _J =150°C)	T _C =25°C	13	A
	T _C =100°C	8	
Pulsed Drain Current	I _{DM}	120	A
Avalanche Energy, Single Pulse (L=0.1mH , T _c =25°C)	E _A	31	mJ
Power Dissipation	T _C =25°C	P _D	W
Operating Junction Temperature		T _J	-55/150 °C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Case	R _{θJC}	0.85	°C/W
Thermal Resistance-Junction to Ambient (steady state)	R _{θJA}	75	



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ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, ID=250uA	100			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , ID=250uA	1.4	1.8	2.4	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V T _J =25°C			1	uA
		V _{DS} =80V, V _{GS} =0V T _J =100°C			100	
Drain-Source On-Resistance	R _{D(on)}	V _{GS} =10V, ID=20A		8.5	9.8	mΩ
		V _{GS} =4.5V, ID=20A		10.5	13	
Forward Transconductance	g _{fs}	V _{DS} =5V, ID=20A		80		S
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =Open, f=1MHz		1.4		Ω
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V		0.9	1.2	V
Dynamic						
Total Gate Charge (10V)	Q _g	V _{DS} =50V, V _{GS} =10V ID=20A		24		nC
Total Gate Charge (4.5V)	Q _g			12		
Gate-Source Charge	Q _{gs}			4		
Gate-Drain Charge	Q _{gd}			6		
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V f=1MHz		1450		pF
Output Capacitance	C _{oss}			273		
Reverse Transfer Capacitance	C _{rss}			5		
Turn-On Time	t _{d(on)}	V _{DD} =50V, ID=20A, V _{GS} =10V R _G =10Ω		6		nS
	t _r			4		
Turn-Off Time	t _{d(off)}			18		
	t _f			3		



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TYPICAL CHARACTERISTICS

Fig 1. Typical Output Characteristics

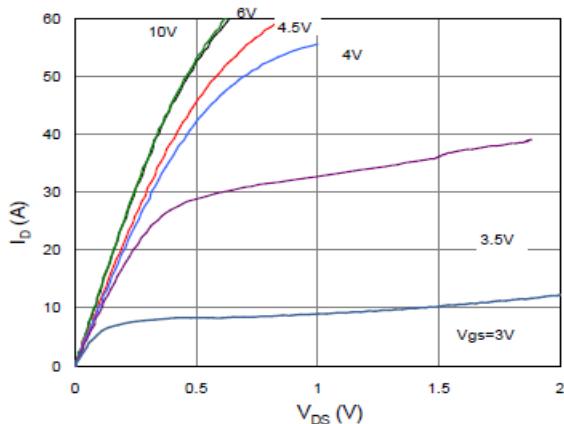


Figure 2. On-Resistance vs. Gate-Source Voltage

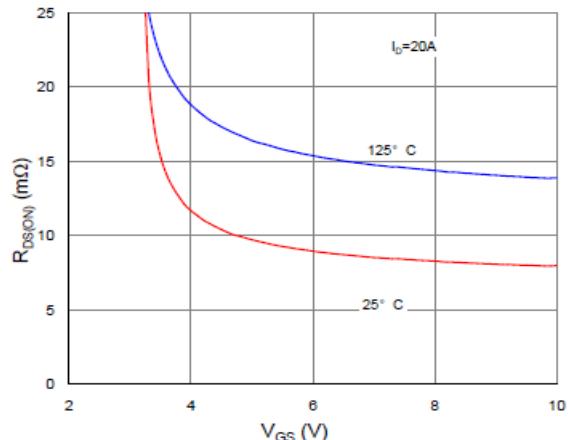


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

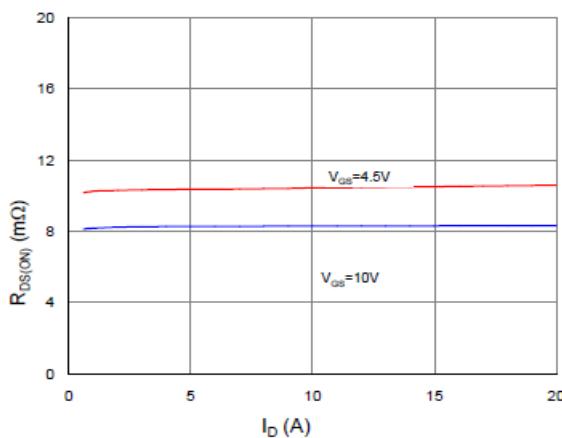


Figure 4. Normalized On-Resistance vs. Junction Temperature

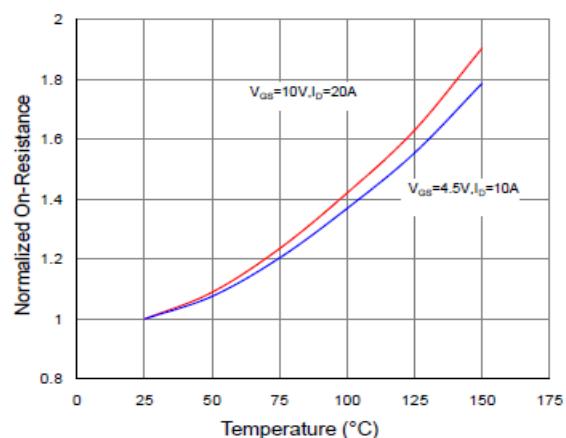


Figure 5. Typical Transfer Characteristics

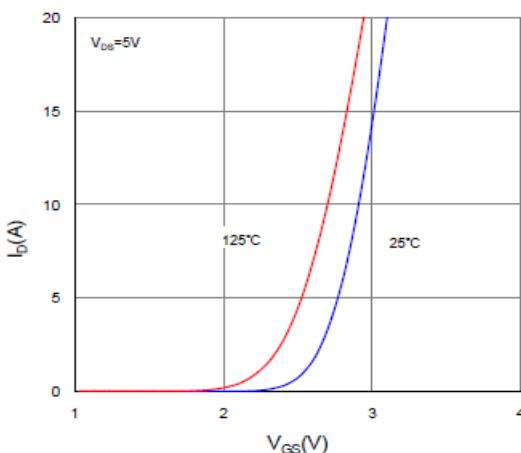
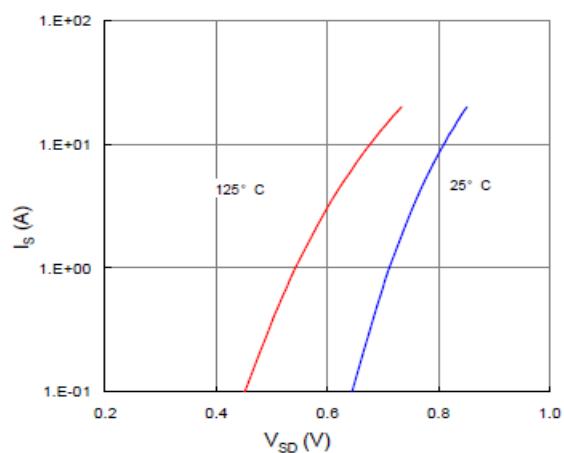


Figure 6. Typical Source-Drain Diode Forward Voltage





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TYPICAL CHARACTERISTICS

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

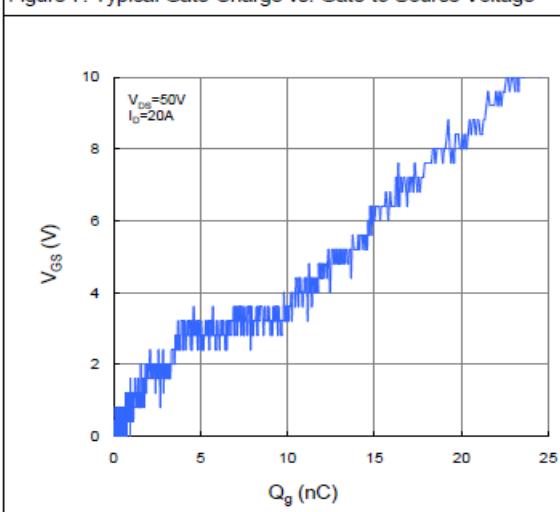


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

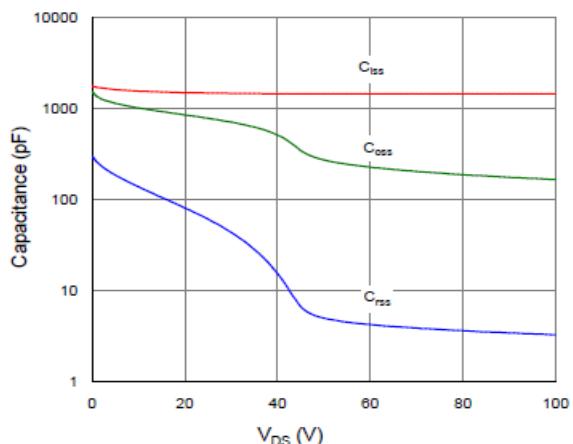


Figure 9. Maximum Safe Operating Area

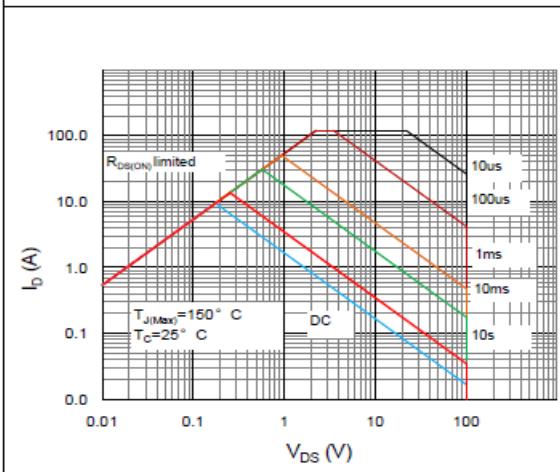


Figure 10. Maximum Drain Current vs. Case Temperature

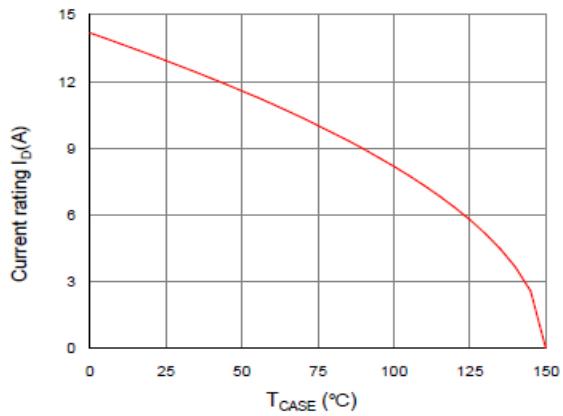
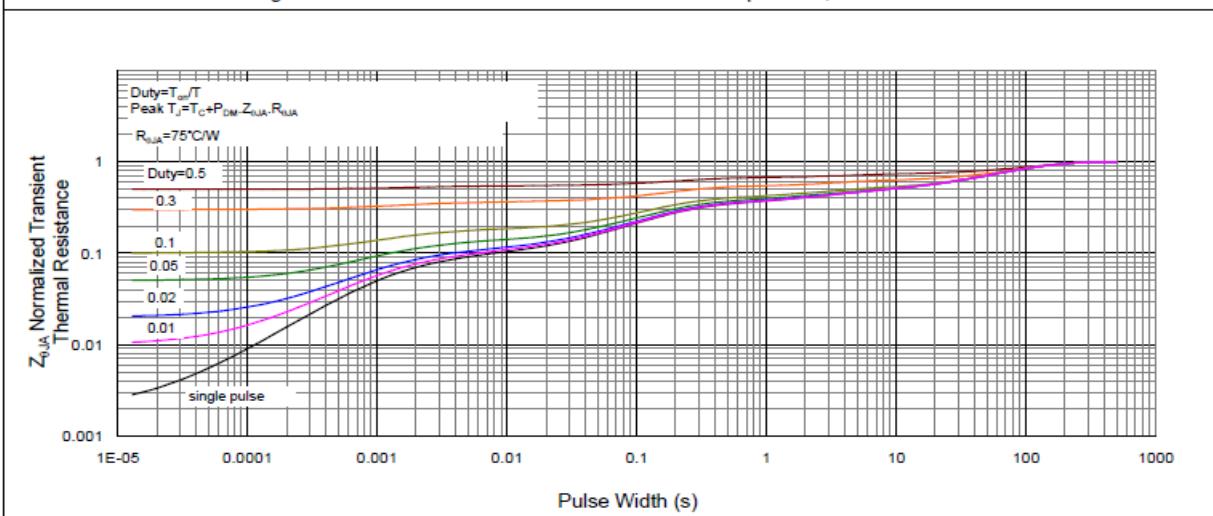


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case





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